

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 5-502: Všeobecné skúšobné metódy na materiály a zostavy Skúšanie zostáv na odolnosť povrchovej izolácie (SIR)	STN EN IEC 61189-5-502 34 6513
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Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-502: General test methods for materials and assemblies - Surface insulation resistance (SIR) testing of assemblies

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/21

Obsahuje: EN IEC 61189-5-502:2021, IEC 61189-5-502:2021

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EN IEC 61189-5-502

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Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-502: General test methods for materials and assemblies - Surface insulation resistance (SIR) testing of assemblies
(IEC 61189-5-502:2021)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 5-502: Méthodes d'essai générales pour les matériaux et les ensembles - Essais de résistance d'isolement en surface (RIS) des ensembles
(IEC 61189-5-502:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 5-502: Allgemeine Prüfverfahren für Materialien und Baugruppen - Prüfung des Oberflächenisolationswiderstands (SIR) von Baugruppen
(IEC 61189-5-502:2021)

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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-5-502:2021 (E)**European foreword**

The text of document 91/1646/CDV, future edition 1 of IEC 61189-5-502, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-5-502:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-10
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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61189-1	NOTE	Harmonized as EN 61189-1
IEC 61189-3	NOTE	Harmonized as EN 61189-3
IEC 61189-5 (series)	NOTE	Harmonized as EN IEC 61189-5 (series)
IEC 61189-6	NOTE	Harmonized as EN 61189-6
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2
IEC 61249-2-7	NOTE	Harmonized as EN 61249-2-7
IEC 62137-4:2014	NOTE	Harmonized as EN 62137-4:2014 (not modified)
ISO 9001	NOTE	Harmonized as EN ISO 9001
ISO 9455-1	NOTE	Harmonized as EN 29455-1
ISO 9455-2	NOTE	Harmonized as EN ISO 9455-2

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-67	-	Environmental testing - Part 2-67: Tests - Test Cy: Damp heat, steady state, accelerated test primarily intended for components	EN 60068-2-67	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications	EN IEC 61190-1-3	-



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Test methods for electrical materials, printed board and other interconnection structures and assemblies –

Part 5-502: General test methods for materials and assemblies – Surface Insulation Resistance (SIR) testing of assemblies

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –

Partie 5-502: Méthodes d'essai générales pour les matériaux et les ensembles – Essais de résistance d'isolement en surface (RIS) des ensembles

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IEC 61189-5-502

Edition 1.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE



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Part 5-502: General test methods for materials and assemblies – Surface Insulation Resistance (SIR) testing of assemblies**

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Partie 5-502: Méthodes d'essai générales pour les matériaux et les ensembles –
Essais de résistance d'isolement en surface (RIS) des ensembles**

INTERNATIONAL
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CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references	6
3 Terms and definitions	7
4 Equipment/Apparatus	7
4.1 Soldering and other production process equipment.....	7
4.2 Measurement instrument.....	7
4.3 Resistor verification coupon	8
4.4 Damp heat chamber.....	8
4.5 Magnifiers (10x – 30x)	9
4.6 Camera.....	9
4.7 Cleaning solvent	9
4.8 Interconnecting cable.....	9
4.9 Connector rack	9
4.10 Solder flux	9
5 Test coupon.....	9
5.1 Test coupon artwork	9
5.1.1 General	9
5.1.2 Test coupon.....	10
5.1.3 Laminate	10
5.1.4 Surface finish	10
5.1.5 Solder mask	10
5.1.6 Quality.....	10
5.2 Components (bill of materials)	10
5.3 Number of test coupons	12
5.4 Test conditions	12
5.5 Coupon identification	13
6 Procedure.....	13
6.1 Test coupon preparation	13
6.2 Cleaning	13
6.3 Manufacturing process replication.....	13
6.4 Preparation of samples for chamber.....	13
6.5 Connector system – High-resistance measurement verification	13
6.6 Hard wiring	14
6.7 Coupon orientation in the chamber	14
6.8 Test coupon measurements	14
6.9 Evaluation.....	15
6.10 Test report	15
6.11 Additional information	16
Annex A (informative) Additional information.....	17
A.1 Additional information	17
A.1.1 General	17
A.1.2 Advisory notes.....	17
A.1.3 Use of coupon test pattern on production product	17
A.2 Use of dummy components	17
A.3 Frequency of monitoring	17

A.4	Condensation.....	18
A.5	Flux volatilisation	18
A.5.1	General	18
A.5.2	90 % RH or 93 % RH	18
A.6	Drip shield	18
A.7	Inspection	19
A.8	Connector test racks	19
A.8.1	Advantages	19
A.8.2	Disadvantages.....	19
A.9	Electromagnetic shielding	19
A.10	Wiring to the IPC B-52 test coupons	20
A.11	Connector test rack wiring.....	21
A.12	Test voltage	21
	Bibliography.....	22
	Figure 1 – Resistor verification coupon using the IPC-B-52 coupon	8
	Figure 2 – IPC B-52 Rev B Top Side.....	11
	Figure 3 – IPC B-52 Rev B bottom side.....	11
	Figure 4 – Test specimen location with respect to chamber air flow	14
	Table 1 – IPC B-52 bill of materials (BOM).....	12
	Table A.1 – IPC B-52 Rev B wiring diagram.....	20

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –**Part 5-502: General test methods for materials and assemblies – Surface Insulation Resistance (SIR) testing of assemblies**

FOREWORD

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IEC 61189-5-502 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1646/CDV	91/1673/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed board and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-502: General test methods for materials and assemblies – Surface Insulation Resistance (SIR) testing of assemblies

1 Scope

This part of IEC 61189 is used for evaluating the changes to the surface insulation resistance of a pre-selected material set on a representative test coupon and quantifies the deleterious effects of improperly used materials and processes that can lead to decreases in electrical resistance.

An assembly process involves a number of different process materials including solder flux, solder paste, solder wire, underfill materials, adhesives, staking compounds, temporary masking materials, cleaning solvents, conformal coatings and more. The test employs two different test conditions of 85 °C and 85 % relative humidity (RH), preferred for a process that includes cleaning, or 40 °C and 90 % relative humidity (RH), preferred for processes where no cleaning is involved.

NOTE 40 °C and 93 % RH can be used as an alternative to 40 °C and 90 % RH. Additional information is provided in 5.4 and A.5.2.

Testing is material (set) and process / equipment specific. Qualifications are to be performed using the production intent equipment, processes and materials.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-20, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-67, *Environmental testing – Part 2-67: Tests – Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61190-1-3, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications*

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